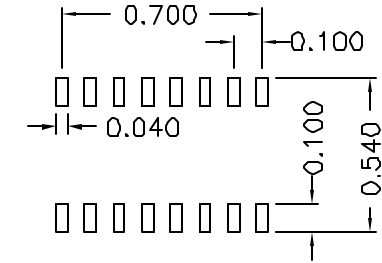
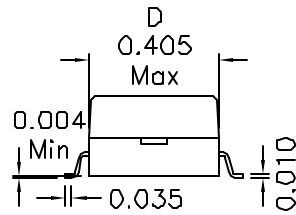
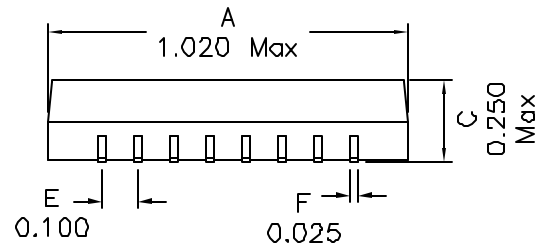


1. Mechanical Dimensions:



SUGGESTED FOOTPRINT

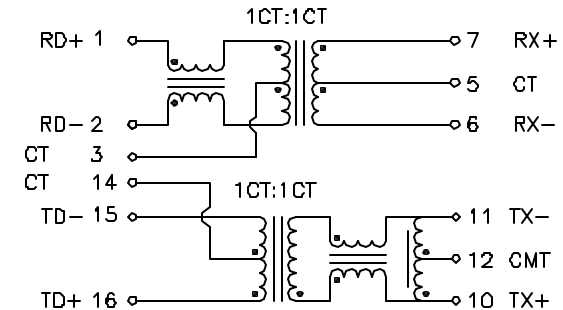
CO-PLANARITY ± 0.004 Max

Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ± 0.004 "(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC. REV: F/17

2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms
 CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA
 Q : 8 Min @100KHz 0.1V
 Rise Time (10-90%): 4.0ns Typ
 Insertion Loss (100KHz-100MHz): -1.0dB Max
 Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz
 -20dB -20dB -18dB -14dB (Min)
 CMRR: 30MHz 60MHz 100MHz
 -42dB -36dB -33dB (Min)
 CROSSTALK: 30MHz 60MHz 100MHz
 -50dB -40dB -40dB (Min)

XFMRS Inc. www.XFMRS.com	Title: HIGH SPEED LAN MAGNETICS		
	UNLESS OTHERWISE SPECIFIED		REV. F
TOLERANCES: .xxx ± 0.010	P/N: XFATM6	DWN.	Mei Chen
Dimensions in Inch	CHK.	YK Liao	Spe-26-11
SHEET 1 OF 1	APP.	Joe Huff	Spe-26-11